Bumped Die Outline Drawing



Package Code: DICE DICEW 1.503 x 2.555 x 0.375 mm Body, 0.150mm Pitch

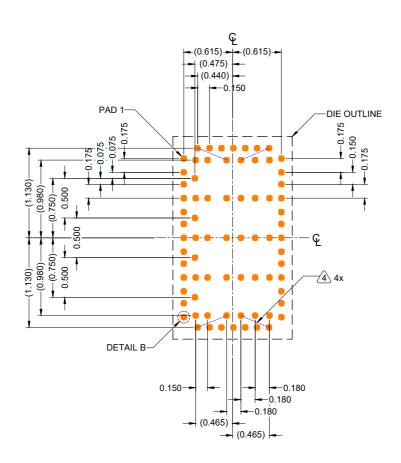
PSC-4930-01, Revision: 00, Date Created: Feb 11, 2022 0.180 0.180 -0.180 0.150-1.503±0.030 (1.130)2.555±0.030 ዒ (0.750)(1.130)00 **TOP VIEW** 74x Ø0.096±0.010 (0.440) (0.475) (0.615) - (0.615) - (0.752) - (0.752) **BOTTOM VIEW** _ 0.075±0.008 0.375±0.050 74x 0.020 C SEATING PLANE DETAIL A C SIDE VIEW -(Ø0.080) UBM (0.005)POLYIMIDE SOLDER BUMP [SnAg; 1.8% Ag] (0.075)**DETAIL A** NOTES:

- 1. All dimensions are in millimeters (mm) and angles are in degrees
- 2. Tolerances of ±0.007mm apply to untoleranced dimensions
- 3. Dimensions in parenthesis () are for reference only

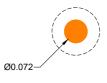
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RECOMMENDED LAND PATTERN (Substrate Top View, NSMD Design)







SIDE VIEW CROSS-SECTION OF BUMP ON PAD FROM DETAIL B

NOTES:

- 1. All dimensions are in millimeters (mm) and angles are in degrees.
- 2. Land Pattern exhibits substrate pads for die bump connections.
- 3. A complete layout requires additional connections and ground patterns.
- Substrate circuit requires networks for redundant die bump connections.

 Land pattern identifies pads to connect, but layout details are not shown.

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